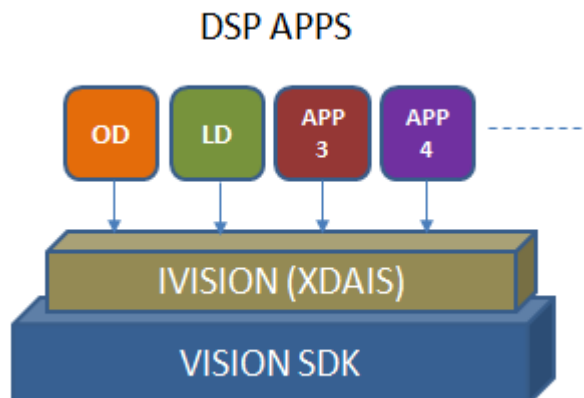




- IVISION (XDAIS) interface compliant
- Validated on TDA2x EVM
- Supports CNN based traffic sign classification
- Identifies 26 different types of German traffic signs.



Description

Object classification module is TI's proprietary Vision and Imaging algorithm implemented on TMS320C66x DSP. Objected classification module is validated with Code Composer Studio version 5.1.0.09000 and code generation tools version 7.4.2.

Performance and Memory Summary

Table 1. Configuration Table

| CONFIGURATION | ID |
|---|--------------|
| CNN based German traffic sign recognition | OBJCLASS_001 |

Table 2. Performance Table

| CONFIGURATION ID | TEST DESCRIPTION | TI C66X DSP PERFORMANCE STATISTICS / OBJECT / FRAME | |
|------------------|--|---|-------------------|
| | | MIN (MEGA CYCLES) | MAX (MEGA CYCLES) |
| OBJCLASS_001 | 1280x720 image pyramid with 13 scales, 32% ROI. List of (X, Y, scale) locations of detected windows from OD module. 1 traffic sign detection | 2.56 | 2.57 |

¹ Performance is validated by running on TDA2x platform. DDR-532Mhz, DSP-600Mhz. The performance of the algorithm will vary depending on the number of objects available in the scene.

Table 3. Memory Statistics - Generated with Code Generation Tools Version 7.4.2

| CONFIGURATION ID | RESOLUTION | MEMORY STATISTICS ¹ | | | | | | |
|------------------|------------|--------------------------------|-------------|-------------|----------|--------|-------|-------|
| | | PROGRAM MEMORY | DATA MEMORY | | | | | TOTAL |
| | | | INTER NAL | EXTERNAL | | | STACK | |
| | | | | PERSIST ENT | SCRAT CH | CONST | | |
| OBJCLASS_001 | 1280x720 | 12.25 | 224 | 20.6 | 240.5 | 363.75 | 8 | 869.1 |

¹ All memory requirements are expressed in kilobytes (1 K-byte = 1024 bytes) and there could be a variation of around 1-2% in the numbers.

Table 4. Internal Data Memory Split-up

| CONFIGURATION ID | DATA MEMORY – INTERNAL ² | | |
|------------------|-------------------------------------|---------|-----------------------|
| | SHARED | | INSTANCE ³ |
| | CONSTANTS | SCRATCH | |
| OBJCLASS_001 | - | 224 | - |

² Internal memory refers to on chip memory. All memory requirements are expressed in kilobytes and there could be a variation of around 1-2% in numbers. L1D memory is configured entirely as 32kb of cache. L2 memory is split as 224kb of SRAM and 64 kb of cache. Executing object classification module along with other DSP algorithms which requires different L1D configuration could hinder performance.

³ I/O buffers are not included. Some of the instance memory buffers could be scratch.

notes

- I/O buffers:
 - Input buffer size = 4097.25 K-bytes (For image pyramid of 1280x720 resolution, 13 scales, 1 frame, 32% ROI)
 - Input buffer size = 1544 bytes (For detected traffic signs from OD module, max of 32 objects per frame)
 - Output buffer size = 1544 bytes (For classified traffic signs from OC module, max of 32 objects per frame)
 - Total data memory for N non pre-emptive instances = Constants + Runtime Tables + Scratch + N * (Instance + I/O buffers + Stack)
- Total data memory for N pre-emptive instances = Constants + Runtime Tables + N * (Instance + I/O buffers + Stack + Scratch)

references

- ObjectClassification_DSP_UserGuide.pdf

glossary

| | |
|-----------|---|
| Constants | Elements that go into .const memory section |
| Scratch | Memory space that can be reused across different instances of the algorithm |
| Shared | Sum of Constants and Scratch |
| Instance | Persistent-memory that contains persistent information - allocated for each instance of the algorithm |



acronyms

| | |
|-----|------------------------------|
| DMA | Direct Memory Access |
| EVM | Evaluation Module |
| CNN | Convolutional Neural Network |

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PRODUCT PREVIEW



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